	Туре	L#	Hits	Search Text	DBs
1	BRS	L1	946	12577783 CCIS	US-PGPUB; USPAT; USOCR
2	BRS	L2	1999	1/5///X/ CCIS	US-PGPUB; USPAT; USOCR
3	BRS	L3	511	UM/I/XX CCIC	US-PGPUB; USPAT; USOCR
4	BRS	L4	158	257/783.ccls.	EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	398 ·	257/788.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	0	((chip or die) and (adheisive or attach or resin or underfill or encapsulat\$3) and (peel\$3 adj stress) and (modulus or elasticity)).clm.	US-PGPUB
8	BRS	L8	0	((chip or die) and (adhesive or attach or resin or underfill or encapsulat\$3) and (peel\$3 adj stress) and (modulus or elasticity)).clm.	US-PGPUB

	Туре	L#	Hits	Search Text	DBs
9	BRS	L9		((chip or die) and (adhesive or attach or resin or underfill or encapsulat\$3) and (coefficient or expansion) and (modulus or elasticity) and reflow).clm.	US-PGPUB
10	BRS	L11	18	257/E23.136.c cls.	US-PGPUB; USPAT; USOCR
11	BRS	L10	9	257/E23.116.c cls.	US-PGPUB; USPAT; USOCR